

IEC SYSTEM FOR MUTUAL RECOGNITION OF TEST CERTIFICATES FOR ELECTRICAL EQUIPMENT (IECEE)
CB SCHEME

CB TEST CERTIFICATE

Product

1) Intel® NUC Rugged Chassis Element (Docking)
2) Intel® NUC Pro Chassis Element (Docking)

Name and address of the applicant

INTEL CORPORATION
2200 MISSION COLLEGE BLVD SANTA CLARA, CA 95054-
1537 USA

Name and address of the manufacturer

INTEL CORPORATION
2200 MISSION COLLEGE BLVD SANTA CLARA, CA 95054-
1537 USA

Name and address of the factory

Note: When more than one factory, please report on page 2

GOLDEN ELITE TECHNOLOGY (SHEN ZHEN) LTD
1 NAN HUAN RD SHAJING BAO AN SHENZHEN
GUANGDONG 518104
CHINA Additional Information on page 2

Ratings and principal characteristics

19 Vdc , 4.74 A

Trademark / Brand (if any)



Type of Customer's Testing Facility (CTF) Stage used

Model / Type Ref.

1) xCMCR1ABx, 2) xCMCM2FBx
See Page 2

Additional information (if necessary may also be reported on page 2)

The report was revised to include technical modification(s)

 Additional Information on page 2

A sample of the product was tested and found to be in conformity with

IEC 60950-1:2005/AMD1:2009, IEC 60950-1:2005/AMD2:2013,
IEC 60950-1:2005

As shown in the Test Report Ref. No. which forms part of this Certificate

ATTCB108119-02 issued on 2020-07-06

This CB Test Certificate is issued by the National Certification Body



- UL (US), 333 Pfingsten Rd IL 60062, Northbrook, USA
- UL (Demko), Borupvang 5A DK-2750 Ballerup, DENMARK
- UL (JP), Marunouchi Trust Tower Main Building 6F, 1-8-3 Marunouchi, Chiyoda-ku, Tokyo 100-0005, JAPAN
- UL (CA), 7 Underwriters Road, Toronto, M1R 3B4 Ontario, CANADA

For full legal entity names see www.ul.com/ncbnames

Date: 2020-07-08

Signature:

Original Issue Date: 2019-10-18

Jan-Erik Storgaard



Model Details:

1) xCMCR1ABx, 2) xCMCM2FBx (where x can be a combination of alphanumeric characters, none or blank)

Additional Information:

Additionally evaluated to EN 60950-1:2006 /A11:2009 /A1:2010 /A12:2011 /A2:2013; National Differences specified in the CB Test Report.

The original report was modified to include the following changes/additions:

Add new construction for new model name: xCMCM2FBx with xCM8xCBx (type A, type B, type C) and xCMB1ABx (type B) as below:

- Add product name: Intel® NUC Pro Chassis Element.
- Add thermal pad (type D)
- Add ambient (35 °C)
- Add enclosure chassis (type B)
- Add heatsink (type B) with DC Fan.
- Add VESA mount (type B) (optional)
- Add daughter board (optional)

Additional information (if necessary)



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